

Chip Scale Review

2015 Editorial Calendar

January • February

Semiconductor industry market update	<ul style="list-style-type: none"> • SEMI European 3D TSV Summit Grenoble, France (Jan 19-21) • APEX Expo San Diego, CA (February 24-26) • BiTS Workshop Mesa, AZ (March 15-18) • IMAPS Device Packaging (DPC) Fountain Hills, AZ (March 16-19) • SEMICON China Shanghai China (March 17-19) • Productronica China Shanghai China (March 17-19)
Next generation device packaging	
3D TSVs	
Bonding challenges for 3D ICs	
3D topography inspection for HVM	
Solid state laser ablation	
Wafer probing	
Advances in test and burn-in sockets	

International Directory of Test and Burn-in Socket Suppliers

Ad Space Close Jan 16 - Ad Materials Deadline Jan 23

March • April

2.5D / 3D Integration	<ul style="list-style-type: none"> • SEMICON South East Asia Penang, Malaysia (Apr 22-24) • MEPTEC MEMS Technology Symposium San Jose, CA (May 20) • IoT Symposium San Jose, CA (May 21) • ECTC San Diego, CA (May 26-29)
Wafer-Level Fan-Out	
RF probe technologies	
Electronic packaging materials	
Package failure analysis	
Flip-chip packaging	
MEMS Standards	
3D MEMS WLP	
Inspection and metrology for advanced wafer packaging	
OSATS update	

International Directory of IC Packaging Foundries

Ad Space Close Feb 27 - Materials Close Mar 6

May • June

Advanced 3D integration challenges	<ul style="list-style-type: none"> • IMAPS Advanced Technology Workshop Dearborn, MI (June 3-4) • IEEE/SW Test Workshop (SWTW) San Diego, CA (June 7-10) • SEMI Europe Packaging Tech Seminar Porto, Portugal (June 18) • SEMICON West San Francisco, CA (July 14-16)
Cu pillar bumping	
Semiconductor packaging for IoT	
Wafer-level CSPs	
Metrology	
Dispensing technologies	
3D thermal simulation in the IC design flow	
Burn-in & test of packaged ICs*	
3D FPGAs	

*Awarded to best paper from BiTS Workshop 2015

Ad Space Close April 28 - Ad Materials Close May 1

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July • August

Thermocompression bonding (part 1)	<ul style="list-style-type: none"> • SEMICON Taiwan Taipei, Taiwan (Sept 2-4) • MEPTEC Medical Microelectronics Conference Portland, OR (Sept 16-17) • SEMI European MEMS Summit Milan, Italy (Sept 17-18)
High temperature electronics	
Glass-based interposer and board-level packaging	
Addressing the challenges of custom and standard MEMS products	
Solder reliability	
Wafer-level packaging	
Optical inspection technologies for 3D packaging	

International Directory of Bonding Equipment for 2.5D and 3D Assembly

Ad Space Close Jun 12 - Ad Materials Close Jun 18

September • October

Thermocompression bonding (part 2)	<ul style="list-style-type: none"> • SEMICON Europa Dresden, Germany (Oct 6-8) • International Test Conference (ITC) Anaheim, CA (Oct 6-8) • IWLPC-International Wafer-Level Packaging Conference & Exhibition San Jose, CA (Oct 13-15) • IMAPS 2015 Orlando, FL (Oct 26-29)
System scaling for smart mobile systems	
Wafer-level packaging processes and performance	
Lithography challenges for 2.5D integration	
Package-level Integration of MEMS in IoT Devices	
Flip chip packaging	
Silicon photonics	
SiPs	
Cost Modeling	

Ad Space Close Aug 14 - Ad Materials Close Aug 21

November • December

3D TSVs	<ul style="list-style-type: none"> • MEMS Executive Congress Napa, CA (Nov 4) • Productronica Munich, Germany (Nov 10-13) • T-Sensors Summit 2015 Celebration, FL (Dec 9-10) • RTI 3D ASIP Conference Burlingame, CA (Dec 9-11) • SEMICON Japan Tokyo, Japan (Dec 16-18) • SEMI European 3D TSV Summit 2016 Grenoble, France (Jan 18-20)
Recent advances in 3D package reliability	
Die stacking	
Heterogeneous integration	
FOWLP	
Wire bonding	
Packaging for extreme environments	
Solving delamination in leadframe-based packages	
The future of semiconductor packaging technology	

Ad Space Close Oct 10 - Materials Close Oct 16